TE Internal #: 2-1761607-2

Wire-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Right Angle,

Through Hole - Solder, 2 Row, Low Profile, Ribbon Cable

Connectors

View on TE.com >

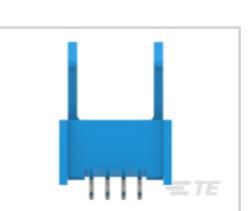


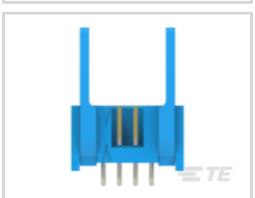
Connectors > PCB Connectors > Wire-to-Board Connectors > FFC, FPC & Ribbon Connectors > Ribbon Cable Connectors











Connector System: Wire-to-Board

Number of Positions: 8

Centerline (Pitch): 2.54 mm [.1 in]
PCB Mount Orientation: Right Angle

Termination Method to PCB: Through Hole - Solder

Features

Product Type Features

Connector System	Wire-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	8
PCB Mount Orientation	Right Angle
Number of Rows	2
Body Features	
Connector Profile	Low
Contact Features	
PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]
Mating Pin Diameter	.64 mm[.025 in]
PCB Contact Termination Area Plating Material	Tin

1 A

Contact Current Rating (Max)



Termination Post & Tail Diameter	.64 mm[.025 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Center
Mating Retention	With
Mating Retention Type	Latch
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Compatible Parts



Customers Also Bought













Documents

Product Drawings

IDC LOW PRO HDR 8P RA LG LAT B

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-1761607-2_D.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2-1761607-2_D.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-1761607-2_D.3d_stp.zip

Wire-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Right Angle, Through Hole - Solder, 2 Row, Low Profile, Ribbon Cable Connectors



English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

English

Agency Approvals

UL Report

English